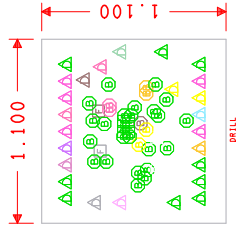


PHYSICAL BOARD DIMENSIONS
& LAYER STRUCTURE

$\frac{.062"}{+/- 10\%}$

_____SILK TOP
_____MASK TOP
_____COMPONENT
_____SOLDER
_____MASK BOTTOM
_____SILK BOTTOM


silkt.art
smaskt.art
layer1.art
layer2.art
smaskb.art
silkb.art



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
⊕	11.0	PLATED	31
⊞	12.0	PLATED	9
△	41.0	PLATED	27

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 2 OZ COPPER.
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED HIP2105DBEVAL1ZA_IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 12 MIL VIAS (9) ARE TO BE THERMAL EPOXY FILLED AND CAPPED.

Drawn By: Tim Klemann	Date Drawn: 01/17/2018	Engineer: Theju Bernard	
Released By:	Date Released:	HIP2105	
Updated By:	Date Updated:	Daughter Board Schematic	
 A Renesas Company	MASK#	HDWR ID	REV.
	HIP2105DBEVAL1ZA		A
FILENAME: ~\HIP2105\HIP2105DBEVAL1ZA		SHEET 1 of 1	